4GB DDR2 – SDRAM SO-DIMM

200 Pin SO-DIMM

SEN04G64D2BJ2WI-xx(W)R

4GByte in FBGA Technology

RoHS compliant

Options:

Data Rate / Latency	Marking
DDR2 533 MT/s CL4	-37
DDR2 667 MT/s CL5	-30

- Module Density
  4096MB with 16 dies and 2 ranks

- Standard Grade (T_A) 0°C to 70°C
  (T_C) 0°C to 85°C
  Grade W (T_A) -40°C to 85°C
  (T_C) -40°C to 95°C

* The refresh rate has to be doubled when 85°C>T_C>95°C

Environmental Requirements:

Operating temperature (ambient)

Standard Grade	0°C to 70°C
Grade W	-40°C to 85°C

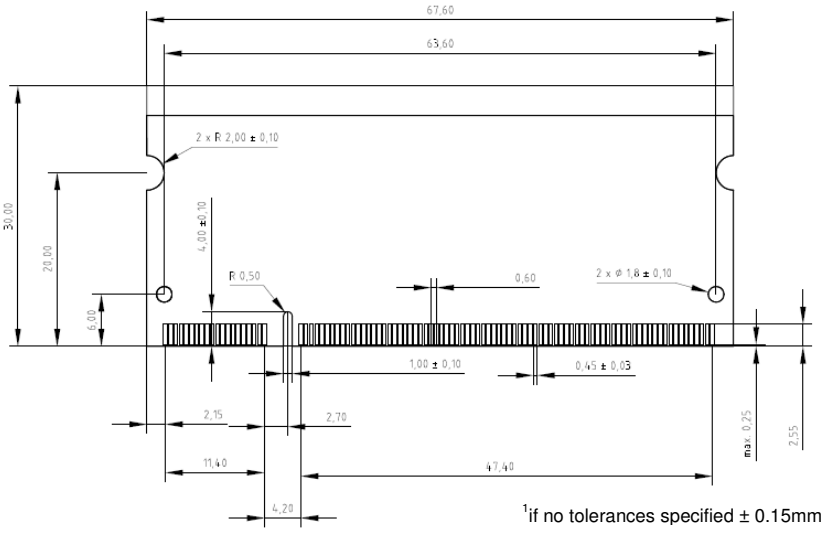
- Operating Humidity
  10% to 90% relative humidity, noncondensing
- Operating Pressure
  105 to 69 kPa (up to 10000 ft.)
- Storage Temperature
  -55°C to 100°C
- Storage Humidity
  5% to 95% relative humidity, noncondensing
- Storage Pressure
  1682 PSI (up to 5000 ft.) at 50°C

Features:

- 200-pin 64-bit Small Outline, Dual-In-Line Double Data Rate Synchronous DRAM Module
- Module organization: dual rank 512M x 64
- VDD = 1.8V ±0.1V, V_{DDQ} 1.8V ±0.1V
- 1.8V I/O (SSTL_18 compatible)
- Auto Refresh (CBR) and Self Refresh 8k Refresh every 64ms
- Serial Presence Detect with EEPROM
- Gold-contact pad
- This module is fully pin and functional compatible to the JEDEC PC2-5300 spec. and JEDEC- Standard MO-224. (see www.jedec.org)
- The pcb and all components are manufactured according to the RoHS compliance specification [EU Directive 2002/95/EC Restriction of Hazardous Substances (RoHS)]

- **DDR2 - SDRAM component Winbond W972GG8JB-30 DIE-Revision J**
- 256Mx8 DDR2 SDRAM in FBGA-60 package
- Four bit prefetch architecture
- DLL to align DQ and DQS transitions with CK
- Eight internal device banks for concurrent operation
- Programmable CAS latency (CL)
- Posted CAS additive latency (AL)
- WRITE latency = READ latency – 1 t_{CK}
- Programmable burst length: 4 or 8
- Adjustable data-output drive strength
- On-die termination (ODT)

Figure: mechanical dimensions[1]



[1]if no tolerances specified ± 0.15mm

This Swissbit module is an industry standard 200-pin 8-byte DDR2 SDRAM Small Outline Dual-In-line Memory Module (SO-DIMM) which is organized as x64 high speed CMOS memory arrays. The module uses internally configured octal-bank DDR2 SDRAM devices. The module uses double data rate architecture to achieve high-speed operation. DDR2 SDRAM modules operate from a differential clock (CK and CK#). READ and WRITE accesses to a DDR2 SDRAM module is burst-oriented; accesses start at a selected location and continue for a programmed number of locations in a programmed sequence. The burst length is either four or eight locations. An auto precharge function can be enabled to provide a self-timed row precharge that is initiated at the end of a burst access. The DDR2 SDRAM devices have a multibank architecture which allows a concurrent operation that is providing a high effective bandwidth. A self refresh mode is provided and a power-saving “power-down” mode. All inputs and all full drive-strength outputs are SSTL_18 compatible.
The DDR2 SDRAM module uses the optional serial presence detect (SPD) function implemented via serial EEPROM using the standard I^2C protocol. This nonvolatile storage device contains 256 bytes. The first 128 bytes are utilized by the SO-DIMM manufacturer (swissbit) to identify the module type, the module’s organization and several timing parameters. The second 128 bytes are available to the end user.

Module Configuration

Organization	DDR2 SDRAMs used	Row Addr.	Device Bank Select	Column Addr.	Refresh	Module Bank Select
512M x 64bit	16 x 256M x 8bit (2048Mbit)	15	BA0, BA1, BA2	10	8k	S0#, S1#

Module Dimensions in mm
67.60 (long) x 30(high) x 3.80 [max] (thickness)

Timing Parameters

Part Number	Module Density	Transfer Rate	Clock Cycle/Data bit rate	Latency
SEN04G64D2BJ2WI-37[W]R	4096 MB	4.2 GB/s	3.7ns / 533MT/s	4-4-4
SEN04G64D2BJ2WI-30[W]R	4096 MB	5.3 GB/s	3.0ns / 667MT/s	5-5-5

Pin Name

A0-9, A11 – A14	Address Inputs
A10/AP	Address Input / Autoprecharge Bit
BA0 – BA2	Bank Address Inputs
DQ0 – DQ63	Data Input / Output
DM0-DM7	Input Data Mask
DQS0 - DQS7	Data Strobe, positive line
DQS0# - DQS7#	Data Strobe, negative line (only used when differential data strobe mode is enabled)
RAS#	Row Address Strobe
CAS#	Column Address Strobe
WE#	Write Enable
CKE0 – CKE1	Clock Enable
CK0 – CK1	Clock Inputs, positive line

CK0# - CK1#	Clock Inputs, negative line
S0# - S1#	Chip Select
V_{DD}	Supply Voltage (1.8V± 0.1V)
V_{REF}	Input / Output Reference
V_{SS}	Ground
V_{DDSPD}	Serial EEPROM Positive Power Supply
SCL	Serial Clock for Presence Detect
SDA	Serial Data Out for Presence Detect
SA0 – SA1	Presence Detect Address Inputs
ODT0 – ODT1	On-Die Termination
NC	No Connection

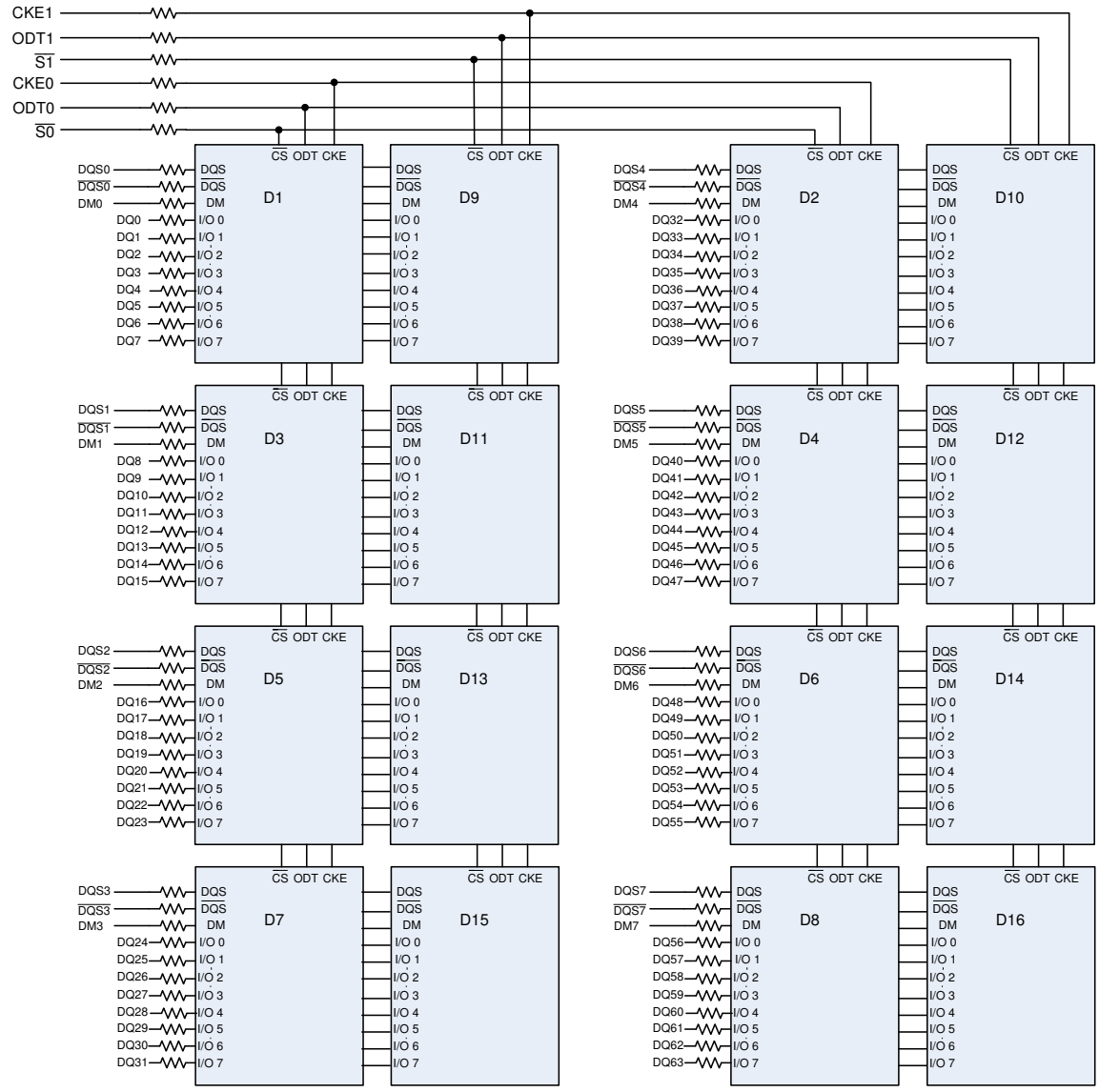
Pin Configuration

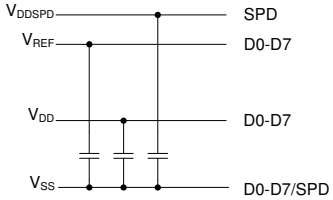
PIN #	Front Side	PIN #	Back Side	PIN #	Front Side	PIN #	Back Side
1	VREF	2	VSS	101	A1	102	A0
3	VSS	4	DQ4	103	VDD	104	VDD
5	DQ0	6	DQ5	105	A10/AP	106	BA1
7	DQ1	8	VSS	107	BA0	108	RAS#
9	VSS	10	DM0	109	WE#	110	S0#
11	DQS0#	12	VSS	111	VDD	112	VDD
13	DQS0	14	DQ6	113	CAS#	114	ODT0
15	VSS	16	DQ7	115	S1#	116	A13
17	DQ2	18	VSS	117	VDD	118	VDD
19	DQ3	20	DQ12	119	ODT1	120	NC (S3)
21	VSS	22	DQ13	121	VSS	122	VSS
23	DQ8	24	VSS	123	DQ32	124	DQ36
25	DQ9	26	DM1	125	DQ33	126	DQ37
27	VSS	28	VSS	127	VSS	128	VSS
29	DQS1#	30	CK0	129	DQS4#	130	DM4
31	DQS1	32	CK0#	131	DQS4	132	VSS
33	VSS	34	VSS	133	VSS	134	DQ38
35	DQ10	36	DQ14	135	DQ34	136	DQ39
37	DQ11	38	DQ15	137	DQ35	138	VSS
39	VSS	40	VSS	139	VSS	140	DQ44
41	VSS	42	VSS	141	DQ40	142	DQ45
43	DQ16	44	DQ20	143	DQ41	144	VSS
45	DQ17	46	DQ21	145	VSS	146	DQS5#
47	VSS	48	VSS	147	DM5	148	DQS5
49	DQS2#	50	NC (EVENT#)	149	VSS	150	VSS

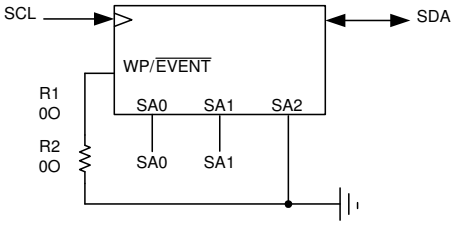
51	DQS2	52	DM2	151	DQ42	152	DQ46
PIN #	**Front Side**	**PIN #**	**Back Side**	**PIN #**	**Front Side**	**PIN #**	**Back Side**
53	Vss	54	Vss	153	DQ43	154	DQ47
55	DQ18	56	DQ22	155	Vss	156	Vss
57	DQ19	58	DQ23	157	DQ48	158	DQ52
59	Vss	60	Vss	159	DQ49	160	DQ53
61	DQ24	62	DQ28	161	Vss	162	Vss
63	DQ25	64	DQ29	163	NC (TEST)	164	CK1
65	Vss	66	Vss	165	Vss	166	CK1#
67	DM3	68	DQS3#	167	DQS6#	168	Vss
69	NC (RESET#)	70	DQS3	169	DQS6	170	DM6
71	Vss	72	Vss	171	Vss	172	Vss
73	DQ26	74	DQ30	173	DQ50	174	DQ54
75	DQ27	76	DQ31	175	DQ51	176	DQ55
77	Vss	78	Vss	177	Vss	178	Vss
79	CKE0	80	CKE1	179	DQ56	180	DQ60
81	VDD	82	VDD	181	DQ57	182	DQ61
83	NC (S2#)	84	NC (A15)	183	Vss	184	Vss
85	BA2	86	A14	185	DM7	186	DQS7#
87	VDD	88	VDD	187	Vss	188	DQS7
89	A12	90	A11	189	DQ58	190	Vss
91	A9	92	A7	191	DQ59	192	DQ62
93	A8	94	A6	193	Vss	194	DQ63
95	VDD	96	VDD	195	SDA	196	Vss
97	A5	98	A4	197	SCL	198	SA0
99	A3	100	A2	199	VDDSPD	200	SA1

(Sig): Signal in brackets may be routed to the socket connector, but is not used on the module

FUNCTIONAL BLOCK DIAGRAMM 4096MB DDR2 SDRAM SODIMM, 2 RANKS AND 16 COMPONENTS







MAXIMUM ELECTRICAL DC CHARACTERISTICS

PARAMETER/ CONDITION		SYMBOL	MIN	MAX	UNITS
Supply Voltage		V_{DD}	-1.0	2.3	V
I/O Supply Voltage		V_{DDQ}	-0.5	2.3	V
Voltage on any pin relative to V_{SS}		V_{IN}, V_{OUT}	-0.5	2.3	V
INPUT LEAKAGE CURRENT Any input 0V ≤ V_{IN} ≤ V_{DD}, V_{REF} pin 0V ≤ V_{IN} ≤ 0.95V (All other pins not under test = 0V)		I_I			µA
	Command/Address RAS#, CAS#, WE#, S#, CKE		-40	40	
	CK, CK#		-20	20	
	DM		-5	5	
OUTPUT LEAKAGE CURRENT (DQ's and ODT are disabled; 0V ≤ V_{OUT} ≤ V_{DDQ})		I_{OZ}	-5	5	µA
	DQ, DQS, DQS#				
V_{REF} LEAKAGE CURRENT ; V_{REF} is on a valid level		I_{VREF}	-16	16	µA

DC OPERATING CONDITIONS

PARAMETER/ CONDITION	SYMBOL	MIN	NOM	MAX	UNITS
Supply Voltage	V_{DD}	1.7	1.8	1.9	V
I/O Supply Voltage	V_{DDQ}	1.7	1.8	1.9	V
I/O Reference Voltage	V_{REF}	0.49 x V_{DDQ}	0.50 x V_{DDQ}	0.51x V_{DDQ}	V
I/O Termination Voltage (system)	V_{TT}	V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04	V
Input High (Logic 1) Voltage	$V_{IH\ (DC)}$	V_{REF} + 0.125		V_{DDQ} + 0.3	V
Input Low (Logic 0) Voltage	$V_{IL\ (DC)}$	-0.3		V_{REF} – 0.125	V

AC INPUT OPERATING CONDITIONS

PARAMETER/ CONDITION	SYMBOL	MIN	MAX	UNITS
Input High (Logic 1) Voltage	$V_{IH\ (AC)}$	V_{REF} + 0.25	-	V
Input Low (Logic 0) Voltage	$V_{IL\ (AC)}$	-	V_{REF} - 0.25	V

CAPACITANCE

At DDR2 data rates, it is recommended to simulate the performance of the module to achieve optimum values. When inductance and delay parameters associated with trace lengths are used in simulations, they are significantly more accurate and realistic than a gross estimation of module capacitance. Simulations can then render a considerably more accurate result. JEDEC modules are now designed by using simulations to close timing budgets.

I_{DD} Specifications and Conditions

(0°C ≤ T_{CASE} ≤ + 85°C; V_{DDQ} = +1.8V ± 0.1V, V_{DD} = +1.8V ± 0.1V)

Parameter & Test Condition		Symbol	Unit		
			5300-555	4200-444	
OPERATING CURRENT *) : One device bank Active-Precharge; t_{RC}= t_{RC} (I_{DD}); t_{CK} = t_{CK} (I_{DD}); CKE is HIGH, CS# is HIGH between valid commands; DQ inputs changing once per clock cycle; Address and control inputs changing once every two clock cycles		I_{DD0}	648	624	mA
OPERATING CURRENT *) : One device bank; Active-Read-Precharge; I_{OUT} = 0mA; BL = 4, CL = CL (I_{DD}), AL = 0; t_{CK} = t_{CK} (I_{DD}), t_{RC}= t_{RC} (I_{DD}), t_{RAS} = t_{RAS} MIN (I_{DD}), t_{RCD} = t_{RCD} (I_{DD}); CKE is HIGH, CS# is HIGH between valid commands; Address inputs changing once every two clock cycles; Data Pattern is same as I_{DD4W}		I_{DD1}	696	656	mA
PRECHARGE POWER-DOWN CURRENT: All device banks idle; Power-down mode; t_{CK} = t_{CK} (I_{DD}); CKE is LOW; All Control and Address bus inputs are not changing; DQ's are floating at V_{REF}		I_{DD2P}	192	192	mA
PRECHARGE QUIET STANDBY CURRENT: All device banks idle; t_{CK} = t_{CK} (I_{DD}); CKE is HIGH, CS# is HIGH; All Control and Address bus inputs are not changing; DQ's are floating at V_{REF}		I_{DD2Q}	672	624	mA
PRECHARGE STANDBY CURRENT: All device banks idle; t_{CK} = t_{CK} (I_{DD}); CKE is HIGH, CS# is HIGH; All other Control and Address bus inputs are changing once every two clock cycles; DQ inputs changing once per clock cycle		I_{DD2N}	736	672	mA
ACTIVE POWER-DOWN CURRENT: All device banks open; t_{CK} = t_{CK} (I_{DD}); CKE is LOW; All Control and Address bus inputs are not changing; DQ's are floating at V_{REF}	Fast PDN Exit MR[12] = 0	I_{DD3P}	256	480	mA
	Slow PDN Exit MR[12] = 1		256	160	mA
ACTIVE STANDBY CURRENT: All device banks open; t_{CK} = t_{CK} (I_{DD}), t_{RAS} = t_{RAS} MAX (I_{DD}), t_{RP} = t_{RP} (I_{DD}); CKE is HIGH, CS# is HIGH between valid commands; All other Control and Address bus inputs are changing once every two clock cycles; DQ inputs changing once per clock cycle		I_{DD3N}	800	720	mA

Parameter & Test Condition	Symbol	Unit		
		5300-555	4200-444	
OPERATING READ CURRENT: All device banks open, Continuous burst reads; One module rank active; I_{OUT} = 0mA; BL = 4, CL = CL (I_{DD}), AL = 0; t_{CK} = t_{CK} (I_{DD}), t_{RAS} = t_{RAS} MAX (I_{DD}), t_{RP} = t_{RP} (I_{DD}); CKE is HIGH, CS# is HIGH between valid commands; Address bus inputs are changing once every two clock cycles; DQ inputs changing once per clock cycle	I_{DD4R}	1056	936	mA
OPERATING WRITE CURRENT: All device banks open, Continuous burst writes; One module rank active; BL = 4, CL = CL (I_{DD}), AL = 0; t_{CK} = t_{CK} (I_{DD}), t_{RAS} = t_{RAS} MAX (I_{DD}), t_{RP} = t_{RP} (I_{DD}); CKE is HIGH, CS# is HIGH between valid commands; Address bus inputs are changing once every two clock cycles; DQ inputs changing once per clock cycle	I_{DD4W}	976	896	mA
BURST REFRESH CURRENT: t_{CK} = t_{CK} (I_{DD}); refresh command at every t_{RFC} (I_{DD}) interval, CKE is HIGH, CS# is HIGH between valid commands; All other Control and Address bus inputs are changing once every two clock cycles; DQ inputs changing once per clock cycle	I_{DD5}	2400	2240	mA
SELF REFRESH CURRENT: CK and CK# at 0V; CKE $\leq 0.2V$; All other Control and Address bus inputs are floating at V_{REF}; DQ's are floating at V_{REF}	I_{DD6}	192	192	mA
OPERATING CURRENT*) : Four device bank interleaving READs, I_{OUT} = 0mA; BL = 4, CL = CL (I_{DD}), AL = t_{RCD} (I_{DD}) – 1 x t_{CK} (I_{DD}); t_{CK} = t_{CK} (I_{DD}), t_{RC} = t_{RC} (I_{DD}), t_{RRD} = t_{RRD} (I_{DD}), t_{RCD} = t_{RCD} (I_{DD}); CKE is HIGH, CS# is HIGH between valid commands; Address bus inputs are not changing during DESELECT; DQ inputs changing once per clock cycle	I_{DD7}	1536	1376	mA

TIMING VALUES USED FOR I_{DD} MEASUREMENT

I_{DD} MEASUREMENT CONDITIONS			
SYMBOL	**5300-555**	**4200-444**	**Unit**
CL (I_{DD})	5	4	t_{CK}
t_{RCD} (I_{DD})	15	15	ns
t_{RC} (I_{DD})	60	60	ns
t_{RRD} (I_{DD})	7.5	7.5	ns
t_{CK} (I_{DD})	3.0	3.75	ns
t_{RAS} MIN (I_{DD})	45	45	ns
t_{RAS} MAX (I_{DD})	70'000	70'000	ns
t_{RP} (I_{DD})	15	15	ns
t_{RFC} (I_{DD})	195	195	ns

DDR2 SDRAM COMPONENT ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS

(0°C ≤ T_{CASE} ≤ + 85°C; V_{DDQ} = +1.8V ± 0.1V, V_{DD} = +1.8V ± 0.1V)

AC CHARACTERISTICS			5300-555		4200-444		Unit
PARAMETER		SYMBOL	MIN	MAX	MIN	MAX	
Clock cycle time	CL = 6	t_{CK} (6)	-	-	-	-	ns
	CL = 5	t_{CK} (5)	3.0	8.0	-	-	ns
	CL = 4	t_{CK} (4)	3.75	8.0	3.75	8.0	ns
	CL = 3	t_{CK} (3)	5.0	8.0	5.0	8.0	ns
CK high-level width		t_{CH}	0.45	0.55	0.45	0.55	t_{CK}
CK low-level width		t_{CL}	0.45	0.55	0.45	0.55	t_{CK}
Half clock period		t_{HP}	min (t_{CH}, t_{CL})		min (t_{CH}, t_{CL})		ps
Access window (output) of DQ_S from CK/CK#		t_{AC}	-0.45	+0.45	-0.50	+0.50	ns
Data-out high-impedance window from CK/CK#		t_{HZ}		+0.45 (= t_{AC} max)		+0.50 (= t_{AC} max)	ns
Data-out low-impedance window from CK/CK#		t_{LZ}	-0.45 (= t_{AC} min)	+0.45 (= t_{AC} max)	-0.50 (= t_{AC} min)	+0.50 (= t_{AC} max)	ns
DQ and DM input setup time relative to DQS		t_{DS}	0.10		0.10		ns
DQ and DM input hold time relative to DQS		t_{DH}	0.30		0.35		ns
DQ and DM input pulse width (for each input)		t_{DIPW}	0.35		0.35		t_{CK}
Data hold skew factor		t_{QHS}		0.34		0.4	ns
DQ-DQS hold, DQS to first DQ to go non-valid, per access		t_{QH}	t_{HP} - t_{QHS}		t_{HP} - t_{QHS}		ns
Data valid output window		t_{DVW}	t_{QH} - t_{DQSQ}		t_{QH} - t_{DQSQ}		ns
DQS input high pulse width		t_{DQSH}	0.35		0.35		t_{CK}
DQS input low pulse width		t_{DQSL}	0.35		0.35		t_{CK}
DQS falling edge to CK rising - setup time		t_{DSS}	0.2		0.2		t_{CK}
DQS falling edge from CK rising - hold time		t_{DSH}	0.2		0.2		t_{CK}
DQS –DQ skew, DQS to last DQ valid, per group, per access		t_{DQSQ}		0.24		0.30	ns
DQS read preamble		t_{RPRE}	0.9	1.1	0.9	1.1	t_{CK}
DQS read postamble		t_{RPST}	0.4	0.6	0.4	0.6	t_{CK}
DQS write preamble		t_{WPRE}	0.35		0.25		t_{CK}
DQS write preamble setup time		t_{WPRES}	0		0		ns
DQS write postamble		t_{WPST}	0.4	0.6	0.4	0.6	t_{CK}
Positive DQS latching edge to associated clock edge		t_{DQSS}	- 0.25	+ 0.25	- 0.25	+ 0.25	t_{CK}
Write command to first DQS latching transition			WL- t_{DQSS}	WL+ t_{DQSS}	WL- t_{DQSS}	WL+ t_{DQSS}	t_{CK}
Address and control input pulse width (for each input)		t_{IPW}	0.6		0.6		t_{CK}
Address and control input setup time		t_{ISa}	0.4		0.5		ns

DDR2 SDRAM COMPONENT ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

(0°C ≤ T_{CASE} ≤ + 85°C; V_{DDQ} = +1.8V ± 0.1V, V_{DD} = +1.8V ± 0.1V)

AC CHARACTERISTICS		5300-555		4200-444		Unit
PARAMETER	SYMBOL	MIN	MAX	MIN	MAX	
Address and control input hold time	t_{IH}	0.4		0.5		ns
CAS# to CAS# command delay	t_{CCD}	2		2		t_{CK}
ACTIVE to ACTIVE (same bank) command period	t_{RC}	60		60		ns
ACTIVE bank *a* to ACTIVE bank *b* command	t_{RRD}	7.5		7.5		ns
ACTIVE to READ or WRITE delay	t_{RCD}	15		15		ns
Four bank Activate period	t_{FAW}	37.5		37.5		ns
ACTIVE to PRECHARGE command	t_{RAS}	40	70,000	40	70,000	ns
Internal READ to precharge command delay	t_{RTP}	7.5		7.5		ns
Write recovery time	t_{WR}	15		15		ns
Auto precharge write recovery + precharge time	t_{DAL}	$t_{WR} + t_{RP}$		$t_{WR} + t_{RP}$		ns
Internal WRITE to READ command delay	t_{WTR}	7.5		7.5		ns
PRECHARGE command period	t_{RP}	15		15		ns
PRECHARGE ALL command period	t_{RPA}	$t_{RP} + t_{CK}$		$t_{RP} + t_{CK}$		ns
LOAD MODE command cycle time	t_{MRD}	2		2		t_{CK}
CKE low to CK, CK# uncertainty	t_{DELAY}	$t_{IS} + t_{CK} + t_{IH}$		$t_{IS} + t_{CK} + t_{IH}$		t_{CK}
REFRESH to ACTIVE or REFRESH to REFRESH command interval	t_{RFC}	195	70,000	195	70,000	ns
Average periodic refresh interval (0℃<= T_{CASE} <= 85 ℃)	t_{REFI}		7.8		7.8	µs
(85℃<= T_{CASE} <= 95 ℃)	$t_{REFI\ (IT)}$		3.9		3.9	
Exit SELF REFRESH to non-READ command	t_{XSNR}	t_{RFC}(min) + 10		t_{RFC}(min) + 10		ns
Exit SELF REFRESH to READ command	t_{XSRD}	200		200		t_{CK}
Exit SELF REFRESH timing reference	t_{ISXR}	t_{IS}		t_{IS}		ps
ODT turn-on delay	t_{AOND}	2	2	2	2	t_{CK}
ODT turn-on	t_{AON}	t_{AC}(min)	t_{AC}(max) + 1,000	t_{AC}(min)	t_{AC}(max) + 1,000	ps
ODT turn-off delay	t_{AOFD}	2.5	2.5	2.5	2.5	t_{CK}
ODT turn-off	t_{AOF}	t_{AC}(min)	t_{AC}(max) + 600	t_{AC}(min)	t_{AC}(max) + 600	ps
ODT turn-on (power-down mode)	t_{AONPD}	t_{AC}(min) + 2,000	2 x t_{CK} + t_{AC}(max) + 1,000	t_{AC}(min) + 2,000	2 x t_{CK} + t_{AC}(max) + 1,000	ps
ODT turn-off (power-down mode)	t_{AOFPD}	t_{AC}(min) + 2,000	2.5 x t_{CK} + t_{AC}(max) + 1,000	t_{AC}(min) + 2,000	2.5 x t_{CK} + t_{AC}(max) + 1,000	ps
ODT to power-down entry latency	t_{ANPD}	3		3		t_{CK}

DDR2 SDRAM COMPONENT ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

(0°C ≤ T_{CASE} ≤ + 85°C; V_{DDQ} = +1.8V ± 0.1V, V_{DD} = +1.8V ± 0.1V)

AC CHARACTERISTICS		5300-555		4200-444		Unit
PARAMETER	SYMBOL	MIN	MAX	MIN	MAX	
ODT power-down exit latency	t_{AXPD}	8		8		t_{CK}
ODT enable from MRS command	T_{MOD}	12		12		ns
Exit active power-down to READ command, MR [bit 12 = 0]	t_{XARD}	2		2		t_{CK}
Exit active power-down to READ command, MR [bit 12 = 1]	t_{XARDS}	7 – AL		6 – AL		t_{CK}
Exit precharge power-down to any non-READ command	t_{XP}	2		2		t_{CK}
CKE minimum high/low time	t_{CKE}	3		3		t_{CK}

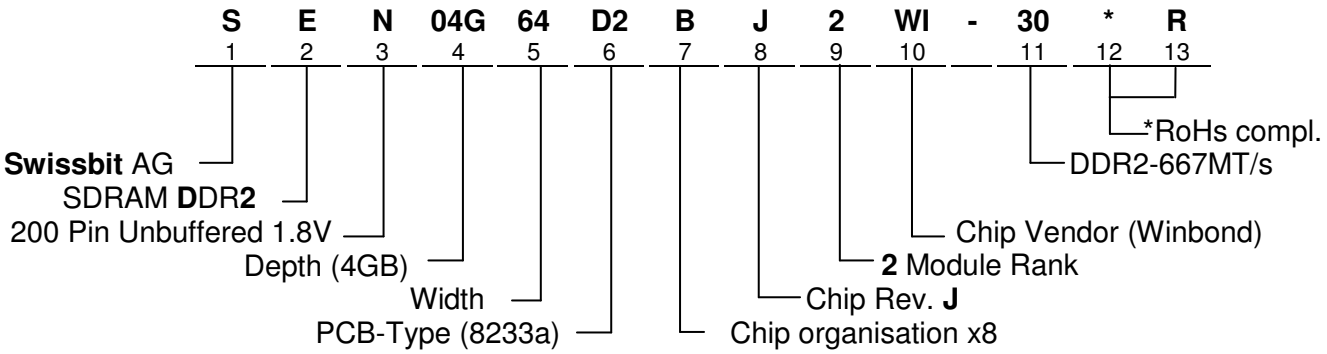
SERIAL PRESENCE-DETECT MATRIX

BYTE	DESCRIPTION	5300-555	4200-444
0	NUMBER OF SPD BYTES USED	0x80	
1	TOTAL NUMBER OF BYTES IN SPD DEVICE	0x08	
2	FUNDAMENTAL MEMORY TYPE	0x08	
3	NUMBER OF ROW ADDRESSES ON ASSEMBLY	0x0F	
4	NUMBER OF COLUMN ADDRESSES ON ASSEMBLY	0x0A	
5	DIMM HIGHT AND MODULE RANKS	0x61	
6	MODULE DATA WIDTH	0x40	
7	MODULE DATA WIDTH (continued)	0x00	
8	MODULE VOLTAGE INTERFACE LEVELS (V_{DDQ})	0x05	
9	SDRAM CYCLE TIME, (t_{CK}) [max CL] CL = 5 (5300), CL = 4 (4200)	0x30 0x3D	
10	SDRAM ACCESS FROM CLOCK, (t_{AC}) [max CL] CL = 5 (5300), CL = 4 (4200)	0x45 0x50	
11	MODULE CONFIGURATION TYPE	0x00	
12	REFRESH RATE / TYPE	0x82	
13	SDRAM DEVICE WIDTH (PRIMARY SDRAM)	0x08	
14	ERROR- CHECKING SDRAM DATA WIDTH	0x00	
15	MINIMUM CLOCK DELAY, BACK-TO-BACK RANDOM COLUMN ACCESS	0x00	
16	BURST LENGTHS SUPPORTED	0x0C	
17	NUMBER OF BANKS ON SDRAM DEVICE	0x08	
18	CAS LATENCIES SUPPORTED	0x38	0x18
19	MODULE THICKNESS	0x01	
20	DDR2 DIMM TYPE	0x04	
21	SDRAM MODULE ATTRIBUTES	0x00	
22	SDRAM DEVICE ATTRIBUTES: Weak Driver and 50Ω ODT	0x03	0x01
23	SDRAM CYCLE TIME, (t_{CK}) [max CL – 1] CL = 4 (5300), CL = 3 (4200)	0x3D	0x50
24	SDRAM ACCESS FROM CK, (t_{AC}) [max CL – 1] CL = 4 (5300), CL = 3 (4200)	0x45	0x50
25	SDRAM CYCLE TIME, (t_{CK}) [max CL – 2] CL = 3 (5300)	0x50	0x00
26	SDRAM ACCESS FROM CK, (t_{AC}) [max CL – 2] CL = 3 (5300)	0x45	0x00
27	MINIMUM ROW PRECHARGE TIME, (t_{RP})	0x3C	
28	MINIMUM ROW ACTIVE TO ROW ACTIVE, (t_{RRD})	0x1E	
29	MINIMUM RAS# TO CAS# DELAY, (t_{RCD})	0x3C	
30	MINIMUM RAS# PULSE WIDTH, (t_{RAS})	0x2D	
31	MODULE BANK DENSITY	0x02	

SERIAL PRESENCE-DETECT MATRIX (continued)

BYTE	DESCRIPTION	5300-555	4200-444
32	ADDRESS AND COMMAND SETUP TIME, (t_{ISb})	0x20	0x25
33	ADDRESS AND COMMAND HOLD TIME, (t_{IHb})	0x27	0x37
34	DATA / DATA MASK INPUT SETUP TIME, (t_{DSb})	0x10	
35	DATA / DATA MASK INPUT HOLD TIME, (t_{DHb})	0x17	0x22
36	WRITE RECOVERY TIME, (t_{WR})	0x3C	
37	WRITE to READ Command Delay, (t_{WTR})	0x1E	
38	READ to PRECHARGE Command Delay, (t_{RTP})	0x1E	
39	Mem Analysis Probe	0x00	
40	Extension for Bytes 41 and 42	0x30	
41	MIN ACTIVE AUTO REFRESH TIME, (t_{RC})	0x39	
42	MINIMUM AUTO REFRESH TO ACTIVE / AUTO REFRESH COMMAND PERIOD, (t_{RFC})	0xC3	
43	SDRAM DEVICE MAX CYCLE TIME, (t_{CKMAX})	0x80	
44	SDRAM DEVICE MAX DQS-DQ SKEW TIME, (t_{DQSQ})	0x18	0x1E
45	SDRAM DEVICE MAX READ DATA HOLD SKEW FACTOR, (t_{QHS})	0x22	0x28
46	PLL Relock Time	0x00	
47-61	Optional Features, not supported	0x00	
62	SPD REVISION	0x13	
63	CHECKSUM FOR BYTES 0-62	0x5D	0x9B
64-66	MANUFACTURER`S JEDEC ID CODE	0x7F	
67	MANUFACTURER`S JEDEC ID CODE (continued)	0xDA	
68-71	RESERVED	0x00	
72	MANUFACTURING LOCATION	0x01 (Switzerland) | 0x02 (Germany) | 0x03 (USA)	
73-90	MODULE PART NUMBER (ASCII)	"SEN04G64D2BJ2WI-xx"	
91	PCB IDENTIFICATION CODE	x	
92	IDENTIFICATION CODE (continued)	x	
93	YEAR OF MANUFACTURE IN BCD	x	
94	WEEK OF MANUFACTURE IN BCD	x	
95-98	MODULE SERIAL NUMBER	x	
99-127	MANUFACTURER-SPECIFIC DATA (RSVD)	x	
128-255	Open for customer use	0xff	

Part Number Code



* optional / additional information

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